

# SN74LVC1G74 Single Positive-Edge-Triggered D-Type Flip-Flop with Clear and Preset

## 1 Features

- Available in the Texas Instruments NanoFree™ package
- Supports 5-V  $V_{CC}$  operation
- Inputs accept voltages to 5.5-V
- Supports down translation to  $V_{CC}$
- Maximum  $t_{pd}$  of 5.9-ns at 3.3-V
- Low power consumption, 10- $\mu$ A maximum  $I_{CC}$
- $\pm 24$ -mA output drive at 3.3-V
- Typical  $V_{OLP}$  (output ground bounce)  $< 0.8$ -V at  $V_{CC} = 3.3$ -V,  $T_A = 25^\circ\text{C}$
- Typical  $V_{OHV}$  (output  $V_{OH}$  undershoot)  $> 2$ -V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- $I_{off}$  supports live insertion, partial-power-down mode, and back-drive protection
- Latch-up performance exceeds 100 mA per JESD 78, class II
- ESD protection exceeds JESD 22
  - 2000-V human-body model
  - 200-V machine model
  - 1000-V charged-device model

## 2 Applications

- Servers
- LED displays
- Network switch
- Telecom infrastructure
- Motor drivers
- I/O expanders

## 3 Description

This single positive-edge-triggered D-type flip-flop is designed for 1.65-V to 5.5-V  $V_{CC}$  operation.

NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

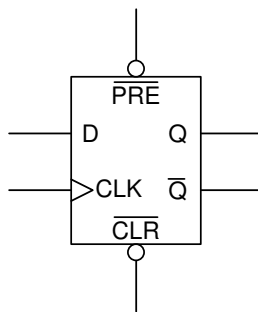
A low level at the preset ( $\overline{PRE}$ ) or clear ( $\overline{CLR}$ ) input sets or resets the outputs, regardless of the levels of the other inputs. When  $\overline{PRE}$  and  $\overline{CLR}$  are inactive (high), data at the data (D) input meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not related directly to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

### Device Information

PART NUMBER	PACKAGE <sup>(1)</sup>	BODY SIZE
SN74LVC1G74	SM8 (8)	2.95 mm × 2.80 mm
	US8 (8)	2.30 mm × 2.00 mm
	X2SON (8)	1.40 mm × 1.00 mm
	UQFN (8)	1.50 mm × 1.50 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



Simplified Schematic

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## 4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

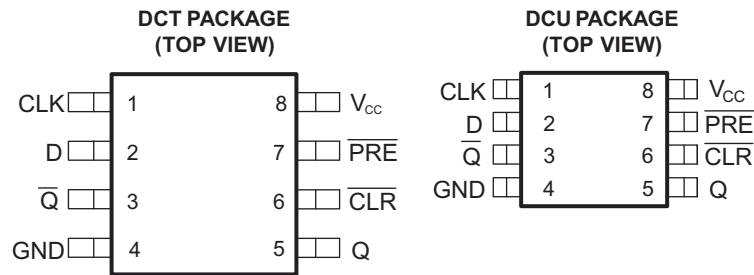
<b>Changes from Revision F (April 2020) to Revision G (September 2021)</b> .....	<b>Page</b>
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	<b>1</b>
• Updated the <i>Application and Information</i> section.....	<b>11</b>
• Updated the <i>Device Power Button Circuit</i> figure <i>Typical Power Button Circuit</i> section.....	<b>11</b>
<b>Changes from Revision E (January 2015) to Revision F (April 2020)</b> .....	<b>Page</b>
• Match RSE pinout with signal names.....	<b>4</b>
<b>Changes from Revision D (January 2013) to Revision E (January 2015)</b> .....	<b>Page</b>
• Added <i>Applications</i> , <i>Device Information</i> table, <i>Pin Functions</i> table, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Typical Characteristics</i> , <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section.....	<b>1</b>
• Deleted <i>Ordering Information</i> table.....	<b>1</b>
• Updated <i>Features</i> .....	<b>1</b>
<b>Changes from Revision C (November 2012) to Revision D (January 2013)</b> .....	<b>Page</b>
• Deleted Thermal data for DQE Package.....	<b>1</b>
• Added Thermal data for DQE Package.....	<b>6</b>
<b>Changes from Revision B (March 2012) to Revision C (November 2012)</b> .....	<b>Page</b>
• Added preview for RES part.....	<b>1</b>
• Added QFN package ordering information.....	<b>14</b>
<b>Changes from Revision A (November 2011) to Revision B (February 2012)</b> .....	<b>Page</b>
• Added SN74LVC1G74DCURG4 part number to ORDERING INFORMATION table.....	<b>14</b>
<b>Changes from Revision * (October 2009) to Revision A (November 2011)</b> .....	<b>Page</b>
• Changed $I_{off}$ description in <i>Features</i> .....	<b>1</b>
• Changed temperature range for DCT and DCU package from (–40°C to 85°C) to (–40°C to 125°C).....	<b>6</b>

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• Changed <i>Timing Requirements</i> table.....	7
• Changed <i>Switching Requirements</i> table.....	7

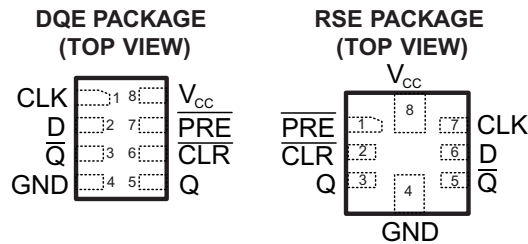
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5 Pin Configuration and Functions



See mechanical drawings for dimensions.

Figure 5-1. DCT 8-Pin SM8 and DCU 8-Pin VSSOP Package Top View



See mechanical drawings for dimensions

Figure 5-2. DQE 8-Pin X2SON and RSE UQFN 8-Pin Package Top View

Pin Functions

PIN		TYPE	DESCRIPTION
NAME	NO.		
CLK	1	I	Clock input
CLR	6	I	Clear input – Pull low to set Q output low
D	2	I	Input
GND	4	—	Ground
PRE	7	I	Preset input – Pull low to set Q output high
Q	5	O	Output
Q	3	O	Inverted output
V <sub>CC</sub>	8	—	Supply

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	−0.5	6.5	V
V <sub>I</sub>	Input voltage range <sup>(2)</sup>	−0.5	6.5	V
V <sub>O</sub>	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	−0.5	6.5	V
V <sub>O</sub>	Voltage range applied to any output in the high or low state <sup>(2)</sup> (3)	−0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		−50 mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		−50 mA
I <sub>O</sub>	Continuous output current			±50 mA
	Continuous current through V <sub>CC</sub> or GND			±100 mA
T <sub>stg</sub>	Storage temperature range	−65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

(3) The value of V<sub>CC</sub> is provided in the *Recommended Operating Conditions* table.

### 6.2 ESD Ratings

PARAMETER	DEFINITION	VALUE	UNIT
V <sub>(ESD)</sub> Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	2000	V
	Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

			MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage	Operating	1.65	5.5	V	
		Data retention only	1.5			
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>		V	
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7			
		V <sub>CC</sub> = 3 V to 3.6 V	2			
		V <sub>CC</sub> = 4.5 V to 5.5 V	0.7 × V <sub>CC</sub>			
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.35 × V <sub>CC</sub>		V	
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.7			
		V <sub>CC</sub> = 3 V to 3.6 V	0.8			
		V <sub>CC</sub> = 4.5 V to 5.5 V	0.3 × V <sub>CC</sub>			
V <sub>I</sub>	Input voltage		0	5.5	V	
V <sub>O</sub>	Output voltage		0	V <sub>CC</sub>	V	
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 1.65 V		−4	mA	
		V <sub>CC</sub> = 2.3 V		−8		
		V <sub>CC</sub> = 3 V		−16		
				−24		
		V <sub>CC</sub> = 4.5 V		−32		
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 1.65 V		4	mA	
		V <sub>CC</sub> = 2.3 V		8		
		V <sub>CC</sub> = 3 V		16		
				24		
		V <sub>CC</sub> = 4.5 V		32		
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V		20	ns/V	
		V <sub>CC</sub> = 3.3 V ± 0.3 V		10		
		V <sub>CC</sub> = 5 V ± 0.5 V		5		
T <sub>A</sub>	Operating free-air temperature	RSE Package	−40	85	°C	
		DQE Package				
		DCT Package	−40	125		
		DCU Package				

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		SN74LVC1G74				UNIT
		DCT	DCU	RSE	DQE	
		8 PINS	8 PINS	8 PINS	8 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	220	227	243	261	°C/W

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

## 6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>OH</sub>		I <sub>OH</sub> = –100 µA	1.65 V to 5.5 V	V <sub>CC</sub> – 0.1			V
		I <sub>OH</sub> = –4 mA	1.65 V	1.2			
		I <sub>OH</sub> = –8 mA	2.3 V	1.9			
		I <sub>OH</sub> = –16 mA	3 V	2.4			
		I <sub>OH</sub> = –24 mA		2.3			
		I <sub>OH</sub> = –32 mA	4.5 V	3.8			
V <sub>OL</sub>		I <sub>OL</sub> = 100 µA	1.65 V to 5.5 V	0.1			V
		I <sub>OL</sub> = 4 mA	1.65 V	0.45			
		I <sub>OL</sub> = 8 mA	2.3 V	0.3			
		I <sub>OL</sub> = 16 mA	3 V	0.4			
		I <sub>OL</sub> = 24 mA		0.55			
		I <sub>OL</sub> = 32 mA	4.5 V	0.55			
I <sub>I</sub>	Data or control inputs	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V	±5			µA
I <sub>off</sub>		V <sub>I</sub> or V <sub>O</sub> = 5.5 V	0	±10			µA
I <sub>CC</sub>		V <sub>I</sub> = 5.5 V or GND, I <sub>O</sub> = 0	1.65 V to 5.5 V	10			µA
ΔI <sub>CC</sub>		One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 5.5 V	500			µA
C <sub>i</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V	5			pF

(1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

## 6.6 Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 7-1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–40°C to 85°C								–40°C to 125°C				UNIT
			V <sub>CC</sub> = 1.8 V		V <sub>CC</sub> = 2.5 V		V <sub>CC</sub> = 3.3 V		V <sub>CC</sub> = 5 V		V <sub>CC</sub> = 3.3 V		V <sub>CC</sub> = 5 V		
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>clock</sub>			80		175		175		200		175		200		MHz
t <sub>w</sub>	CLK		6.2		2.7		2.7		2		2.7		2		ns
	PRE or CLR low		6.2		2.7		2.7		2		2.7		2		
t <sub>su</sub>	Data		2.9		1.7		1.3		1.1		1.3		1.1		ns
	PRE or CLR inactive		1.9		1.4		1.2		1		1.2		1.2		
t <sub>h</sub>			0		0.3		1.2		0.5		1.2		0.5		ns

## 6.7 Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 7-1)

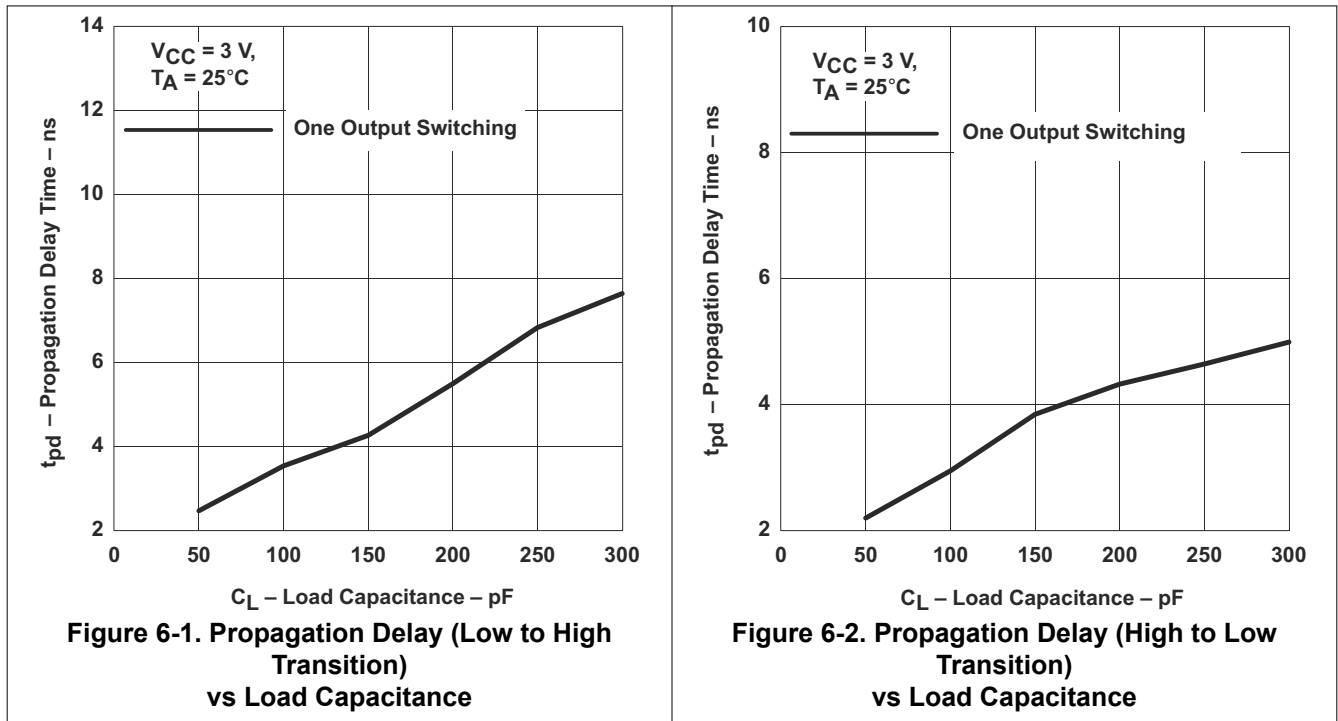
Over recommended operating free air temperature range (unless otherwise noted) (see Figure 7-1)															
PARAMETER	FROM (INPUT)	TO (OUTPUT)	–40°C to 85°C								–40°C to 125°C				UNIT
			V <sub>CC</sub> = 1.8 V		V <sub>CC</sub> = 2.5 V		V <sub>CC</sub> = 3.3 V		V <sub>CC</sub> = 5 V		V <sub>CC</sub> = 3.3 V		V <sub>CC</sub> = 5 V		
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			80		175		175		200		175		200		MHz
t <sub>pd</sub>	CLK	Q	4.8	13.4	2.2	7.1	2.2	5.9	1.4	4.1	2.2	7.9	1.4	6.1	ns
		$\overline{Q}$	6	14.4	3	7.7	2.6	6.2	1.6	4.4	2.6	8.2	1.6	6.4	
	$\overline{PRE}$ or $\overline{CLR}$ low	Q or $\overline{Q}$	4.4	12.9	2.3	7	1.7	5.9	1.6	4.1	1.7	7.9	1.6	6.1	

6.8 Operating Characteristics

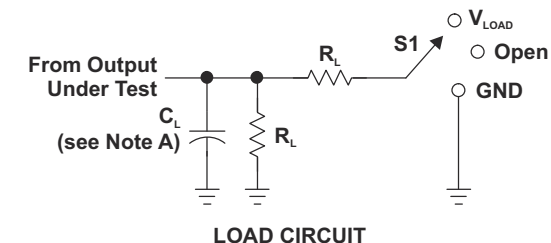
T<sub>A</sub> = 25°C

PARAMETER	TEST CONDITIONS	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	V <sub>CC</sub> = 5 V	UNIT
		TYP	TYP	TYP	TYP	
C <sub>pd</sub> Power dissipation capacitance	f = 10 MHz	35	35	37	40	pF

6.9 Typical Characteristics

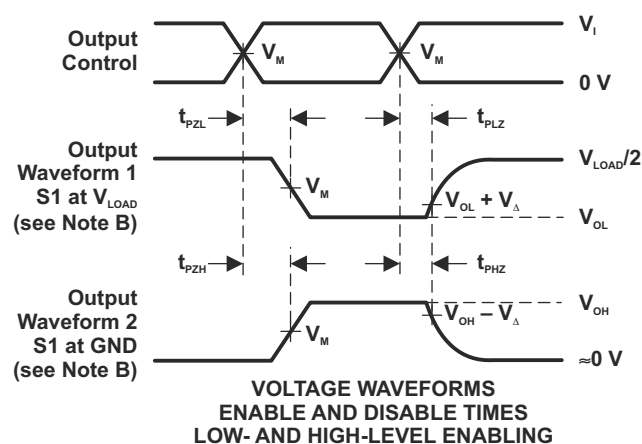
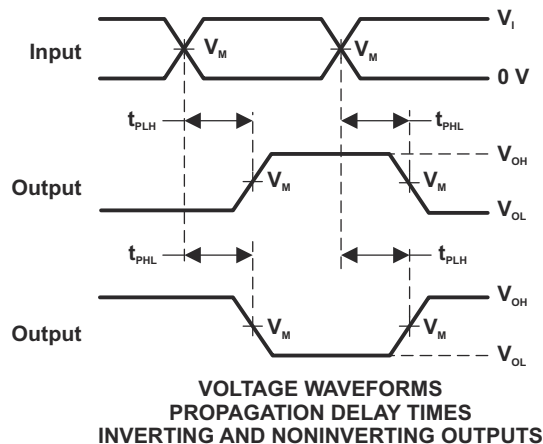
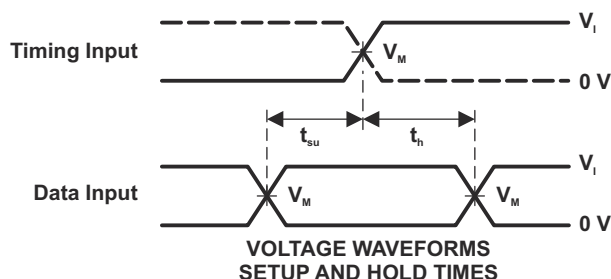
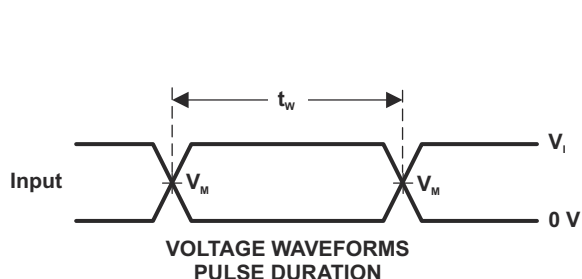


## 7 Parameter Measurement Information



TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_f/t_r$					
$1.8\text{ V} \pm 0.15\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
$3.3\text{ V} \pm 0.3\text{ V}$	3 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
$5\text{ V} \pm 0.5\text{ V}$	$V_{CC}$	$\leq 2.5\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	50 pF	500 $\Omega$	0.3 V



- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics: PRR  $\leq 10\text{ MHz}$ ,  $Z_o = 50\ \Omega$ .
  - The outputs are measured one at a time, with one transition per measurement.
  - $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - All parameters and waveforms are not applicable to all devices.

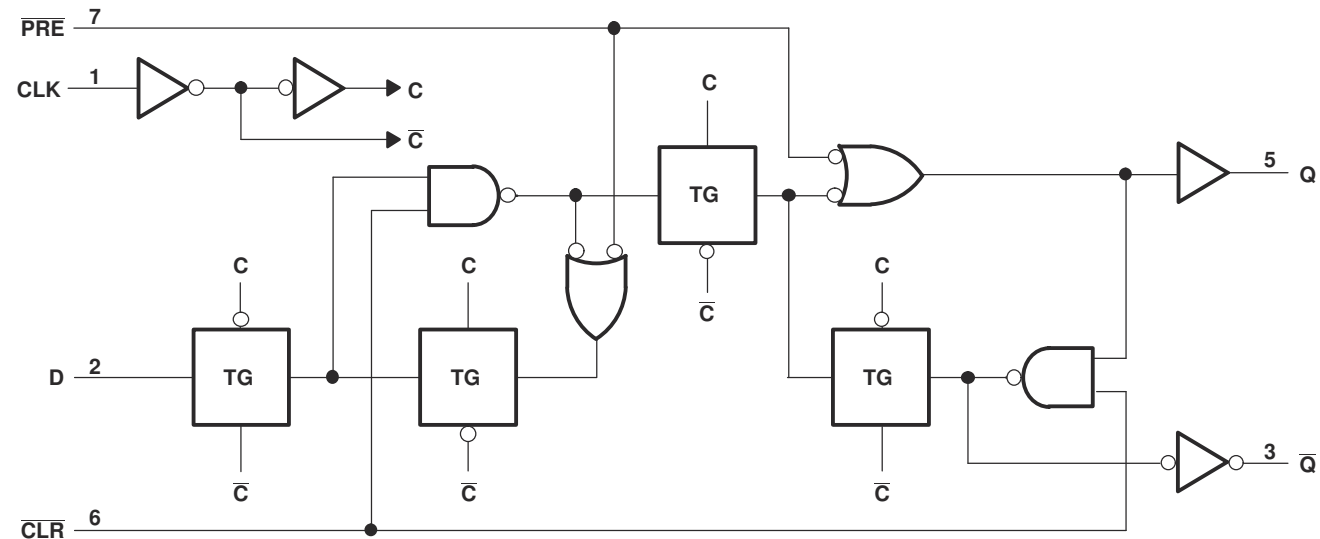
Figure 7-1. Load Circuit and Voltage Waveforms

## 8 Detailed Description

### 8.1 Overview

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

### 8.2 Functional Block Diagram



### 8.3 Feature Description

- Allow down voltage translation
  - 5-V to 3.3-V
  - 5.0-V to 1.8-V
  - 3.3-V to 1.8-V
- Inputs accept voltage levels up to 5.5-V
- $I_{off}$  Feature
  - Can prevent backflow current that can damage device when powered down

### 8.4 Device Functional Modes

Table 8-1. Function Table

INPUTS				OUTPUTS	
PRE	CLR	CLK	D	Q	Q̄
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H <sup>(1)</sup>	H <sup>(1)</sup>
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q <sub>0</sub>	Q̄ <sub>0</sub>

(1) This configuration is nonstable; that is, it does not persist when  $\overline{\text{PRE}}$  or  $\overline{\text{CLR}}$  returns to its inactive (high) level.

## 9 Application and Implementation

### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

### 9.1 Application Information

A low level at the preset ( $\overline{\text{PRE}}$ ) or clear ( $\overline{\text{CLR}}$ ) input sets or resets the outputs, regardless of the levels of the other inputs. When  $\overline{\text{PRE}}$  and  $\overline{\text{CLR}}$  are inactive (high), data at the data (D) input meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not related directly to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

The 330  $\Omega$  resistor and 22 pF capacitor shown in Figure 9-1 produce enough delay to meet the hold time requirement of the D input. To calculate the delay for a particular RC combination, use Equation 1. The delay with this RC combination is 5.03 ns

$$t_{\text{delay}} = -RC \ln(0.5) \approx 0.693 RC \quad (1)$$

To ensure proper operation, check that the transition time of the RC circuit meets the transition time requirements of the device inputs listed in the Recommended Operating Conditions table. Transition time for an RC can be approximated with Equation 2.

$$t_t \approx 2.2 RC \quad (2)$$

### 9.2 Typical Power Button Circuit

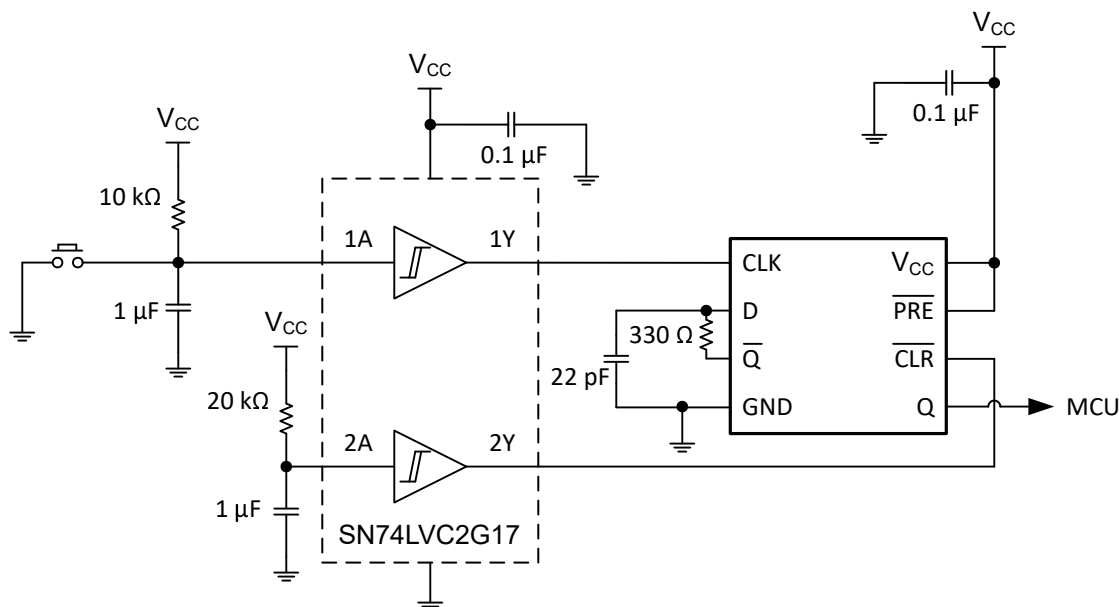


Figure 9-1. Device Power Button Circuit

### 9.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. Outputs can be combined to produce higher drive but the high drive will also create faster edges into light loads so routing and load conditions should be considered to prevent ringing.

### 9.2.2 Detailed Design Procedure

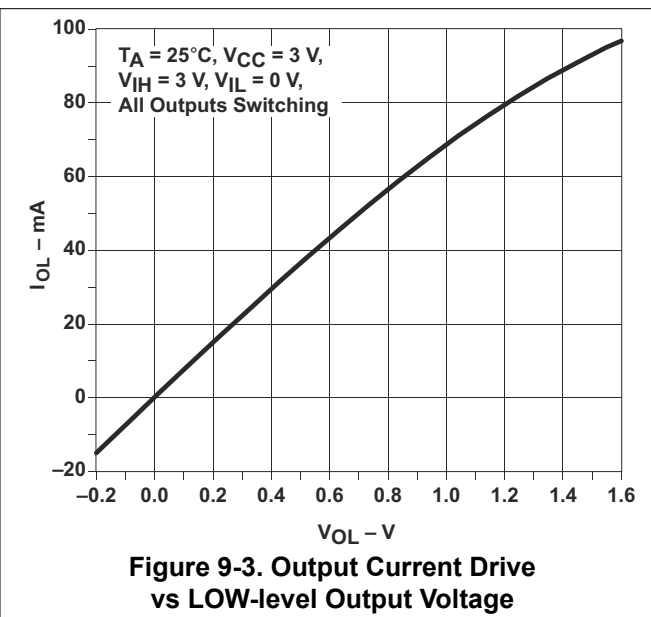
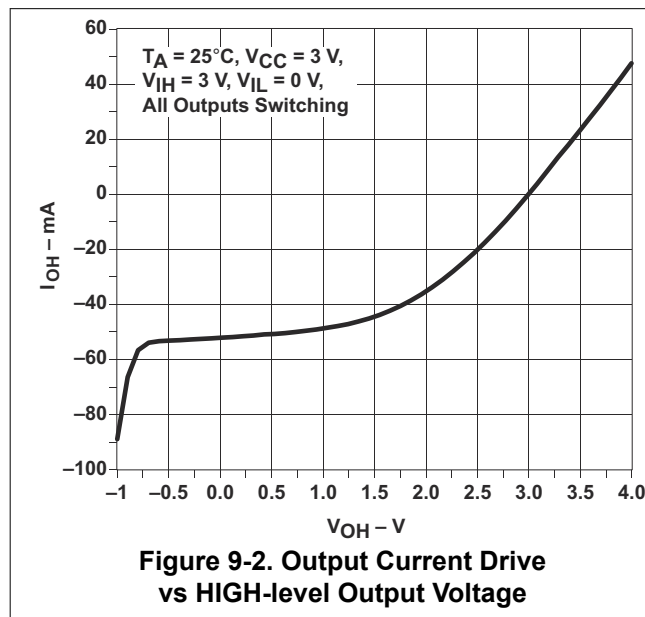
#### 1. Recommended Input Conditions:

- For rise time and fall time specifications, see  $(\Delta t/\Delta V)$  in the [Recommended Operating Conditions](#) table.
- For specified high and low levels, see  $(V_{IH}$  and  $V_{IL})$  in the [Recommended Operating Conditions](#) table.
- Inputs are overvoltage tolerant allowing them to go as high as 5.5-V at any valid  $V_{CC}$ .

#### 2. Recommend Output Conditions:

- Load currents should not exceed 50-mA per output and 100-mA total for the part.
- Series resistors on the output may be used if the user desires to slow the output edge signal or limit the output current.

### 9.2.3 Application Curves



## 10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the [Recommended Operating Conditions](#) table. Each  $V_{CC}$  terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1- $\mu$ F capacitor is recommended and if there are multiple  $V_{CC}$  terminals then .01- $\mu$ F or .022- $\mu$ F capacitors are recommended for each power terminal. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- $\mu$ F and 1- $\mu$ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

## 11 Layout

### 11.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states.

Specified in [Figure 11-1](#) are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or  $V_{CC}$ , whichever makes more sense or is more convenient. It is acceptable to float outputs unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the outputs section of the part when asserted. This will not disable the input section of the I/Os so they also cannot float when disabled.

### 11.2 Layout Example

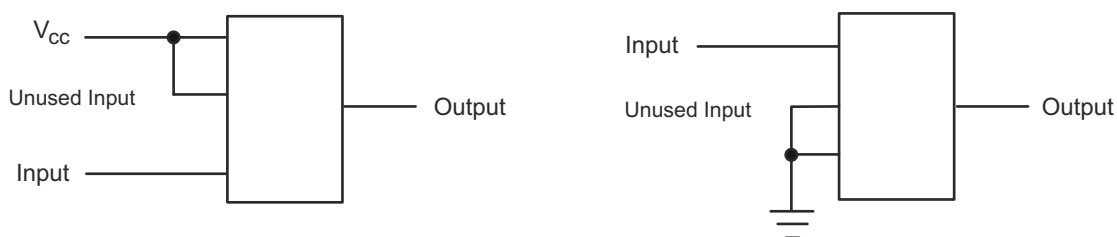


Figure 11-1. Layout Diagram

## 12 Device and Documentation Support

### 12.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](http://ti.com). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 12.2 Support Resources

TI E2E™ [support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 12.3 Trademarks

NanoFree™ is a trademark of Texas Instruments.

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

### 12.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 12.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVC1G74DCTR	ACTIVE	SM8	DCT	8	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	N74 Z	<a href="#">Samples</a>
SN74LVC1G74DCUR	ACTIVE	VSSOP	DCU	8	3000	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	(N74J, N74Q, N74R)	<a href="#">Samples</a>
SN74LVC1G74DCURG4	ACTIVE	VSSOP	DCU	8	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	N74R	<a href="#">Samples</a>
SN74LVC1G74DCUT	ACTIVE	VSSOP	DCU	8	250	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	(N74J, N74Q, N74R)	<a href="#">Samples</a>
SN74LVC1G74DQER	ACTIVE	X2SON	DQE	8	5000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	DP	<a href="#">Samples</a>
SN74LVC1G74RSE2	ACTIVE	UQFN	RSE	8	5000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	DP	<a href="#">Samples</a>
SN74LVC1G74RSER	ACTIVE	UQFN	RSE	8	5000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	DP	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

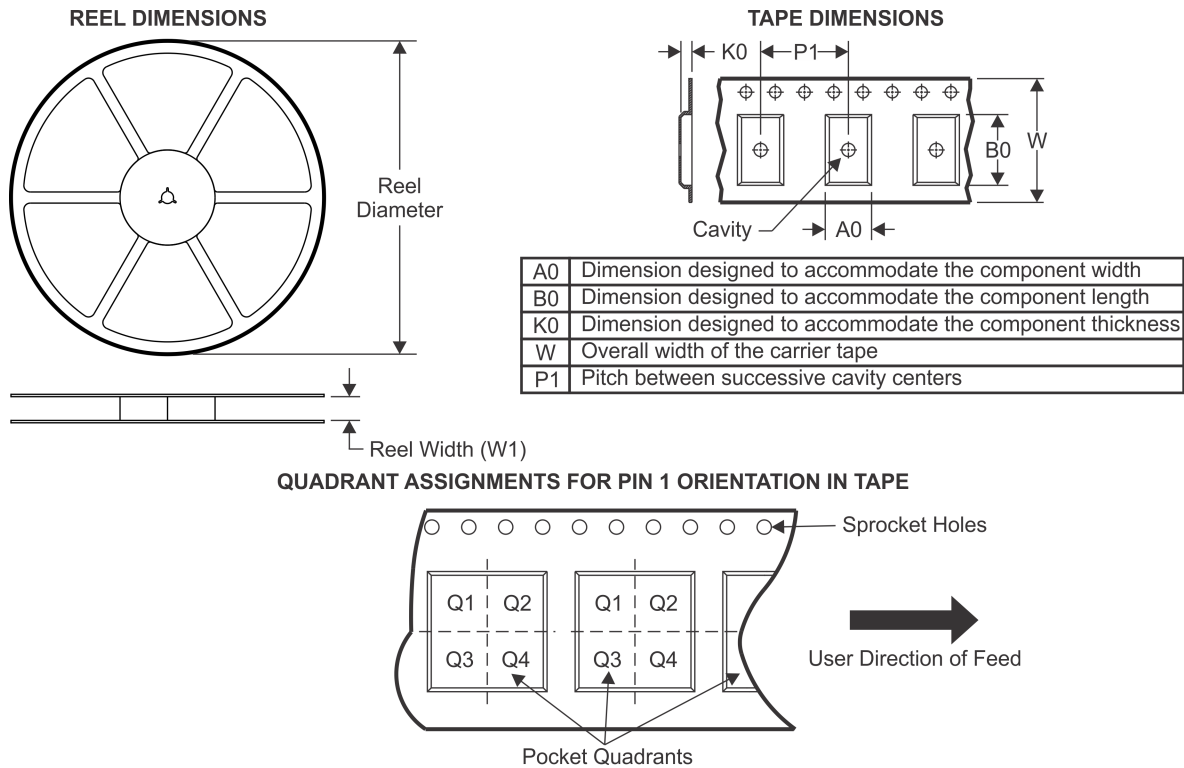
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## TAPE AND REEL INFORMATION



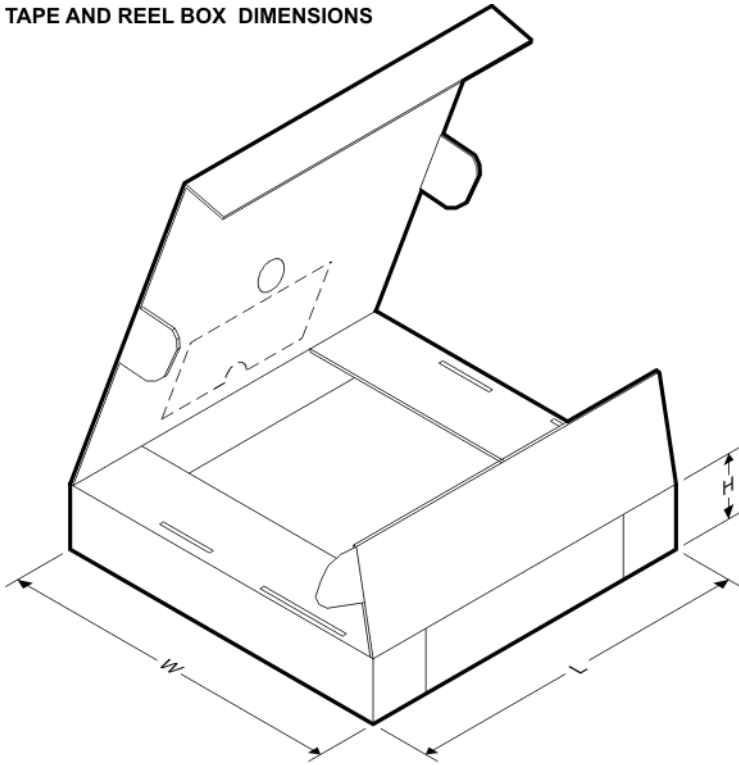
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC1G74DCTR	SM8	DCT	8	3000	180.0	13.0	3.35	4.5	1.55	4.0	12.0	Q3
SN74LVC1G74DCUR	VSSOP	DCU	8	3000	178.0	9.5	2.25	3.35	1.05	4.0	8.0	Q3
SN74LVC1G74DCUR	VSSOP	DCU	8	3000	178.0	9.0	2.25	3.35	1.05	4.0	8.0	Q3
SN74LVC1G74DCUR	VSSOP	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
SN74LVC1G74DCURG4	VSSOP	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
SN74LVC1G74DCUT	VSSOP	DCU	8	250	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
SN74LVC1G74DCUT	VSSOP	DCU	8	250	178.0	9.0	2.25	3.35	1.05	4.0	8.0	Q3
SN74LVC1G74DCUT	VSSOP	DCU	8	250	178.0	9.5	2.25	3.35	1.05	4.0	8.0	Q3
SN74LVC1G74DQER	X2SON	DQE	8	5000	180.0	9.5	1.15	1.6	0.5	4.0	8.0	Q1
SN74LVC1G74RSE2	UQFN	RSE	8	5000	180.0	9.5	1.7	1.7	0.75	4.0	8.0	Q3
SN74LVC1G74RSER	UQFN	RSE	8	5000	180.0	9.5	1.7	1.7	0.75	4.0	8.0	Q2

# PACKAGE MATERIALS INFORMATION

26-Jul-2021

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC1G74DCTR	SM8	DCT	8	3000	182.0	182.0	20.0
SN74LVC1G74DCUR	VSSOP	DCU	8	3000	202.0	201.0	28.0
SN74LVC1G74DCUR	VSSOP	DCU	8	3000	180.0	180.0	18.0
SN74LVC1G74DCUR	VSSOP	DCU	8	3000	202.0	201.0	28.0
SN74LVC1G74DCURG4	VSSOP	DCU	8	3000	202.0	201.0	28.0
SN74LVC1G74DCUT	VSSOP	DCU	8	250	202.0	201.0	28.0
SN74LVC1G74DCUT	VSSOP	DCU	8	250	180.0	180.0	18.0
SN74LVC1G74DCUT	VSSOP	DCU	8	250	202.0	201.0	28.0
SN74LVC1G74DQER	X2SON	DQE	8	5000	184.0	184.0	19.0
SN74LVC1G74RSE2	UQFN	RSE	8	5000	184.0	184.0	19.0
SN74LVC1G74RSER	UQFN	RSE	8	5000	184.0	184.0	19.0

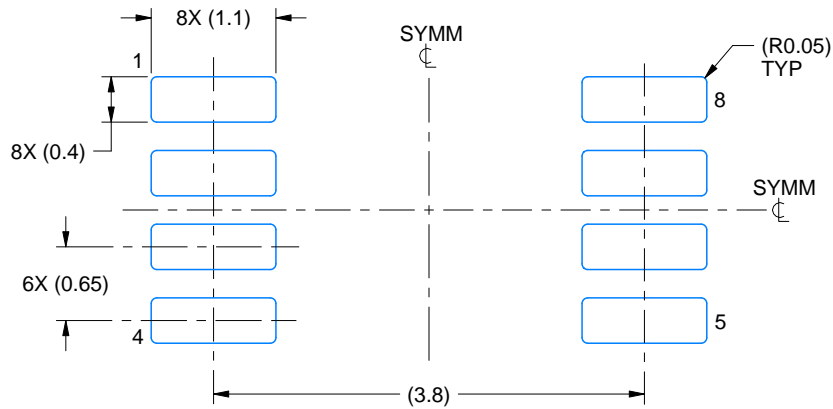


# EXAMPLE BOARD LAYOUT

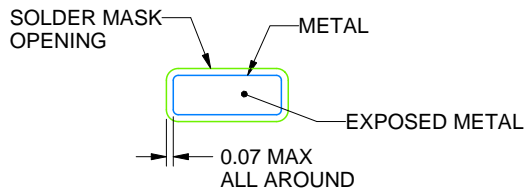
DCT0008A

SSOP - 1.3 mm max height

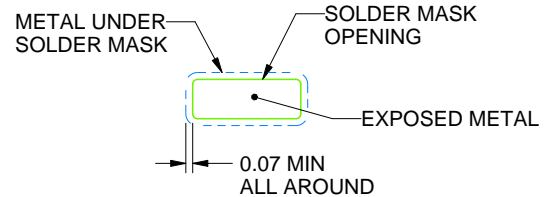
SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:15X



NON SOLDER MASK  
DEFINED



SOLDER MASK  
DEFINED

SOLDER MASK DETAILS

4220784/C 06/2021

NOTES: (continued)

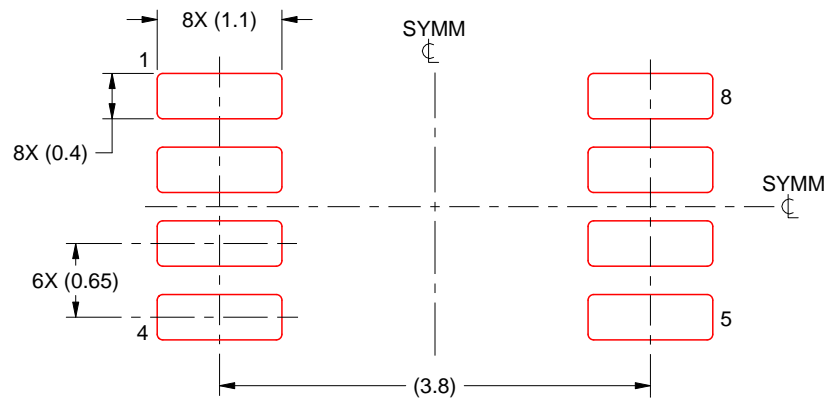
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

DCT0008A

SSOP - 1.3 mm max height

SMALL OUTLINE PACKAGE

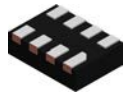


SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:15X

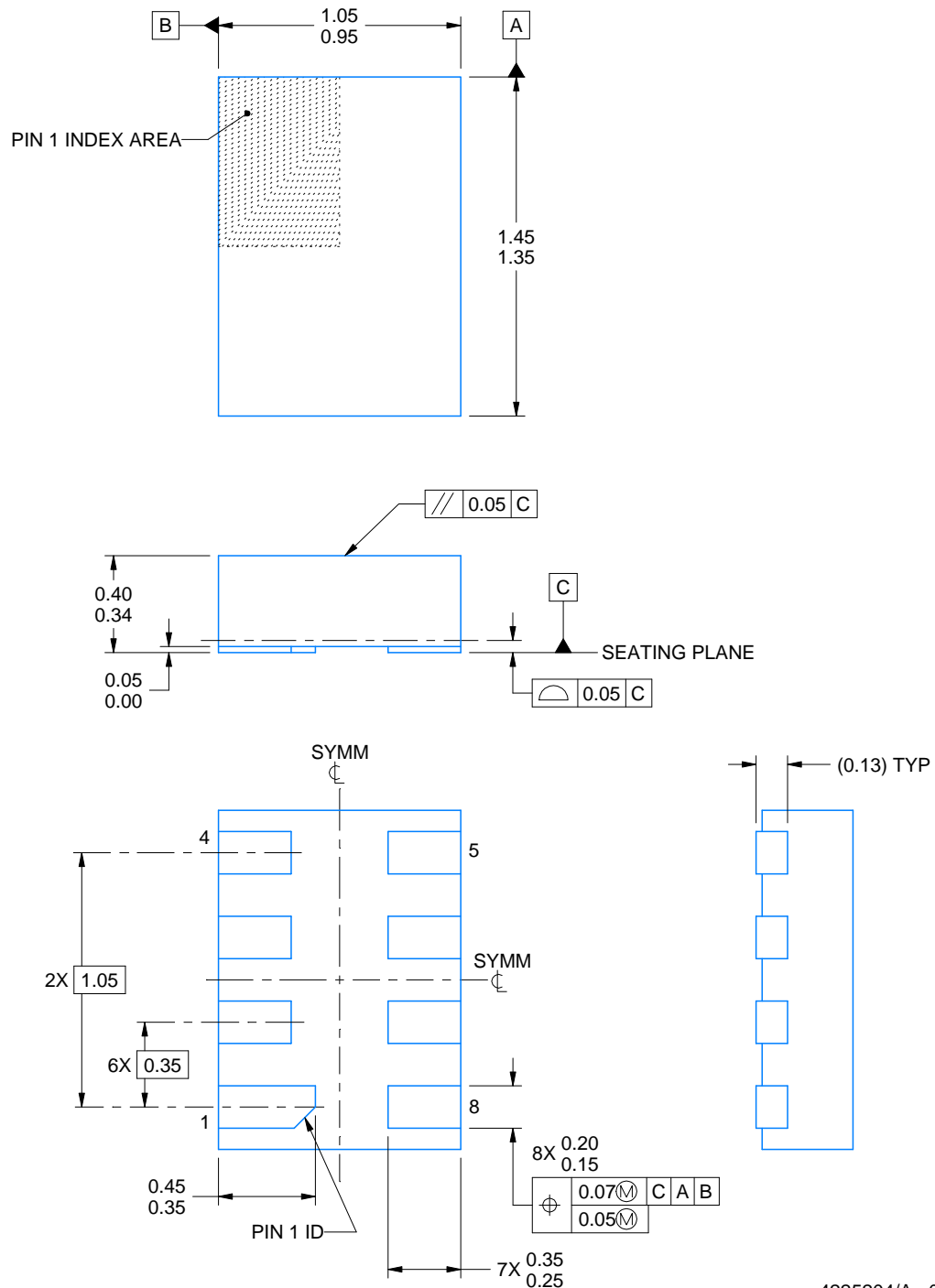
4220784/C 06/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

**DQE0008A****PACKAGE OUTLINE****X2SON - 0.4 mm max height**

PLASTIC SMALL OUTLINE - NO LEAD



4225204/A 08/2019

**NOTES:**

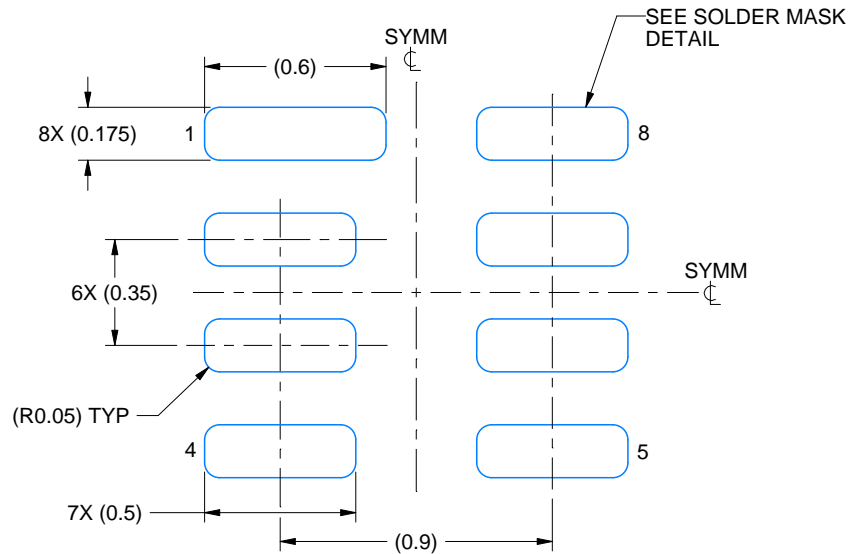
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package complies to JEDEC MO-287 variation X2EAF.

# EXAMPLE BOARD LAYOUT

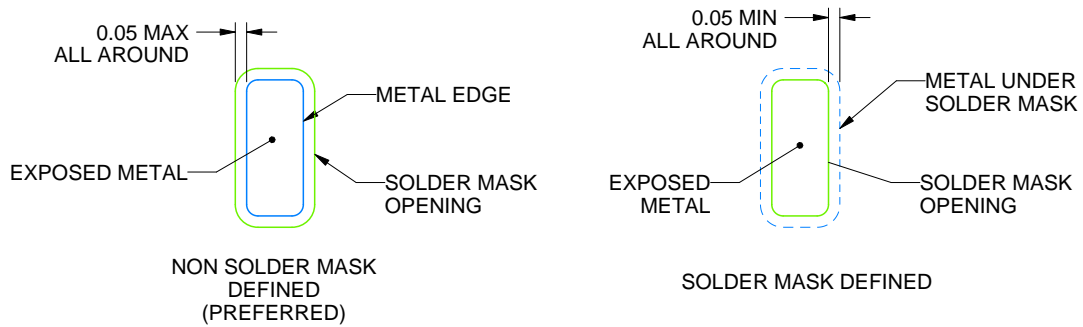
DQE0008A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 40X



SOLDER MASK DETAILS

4225204/A 08/2019

NOTES: (continued)

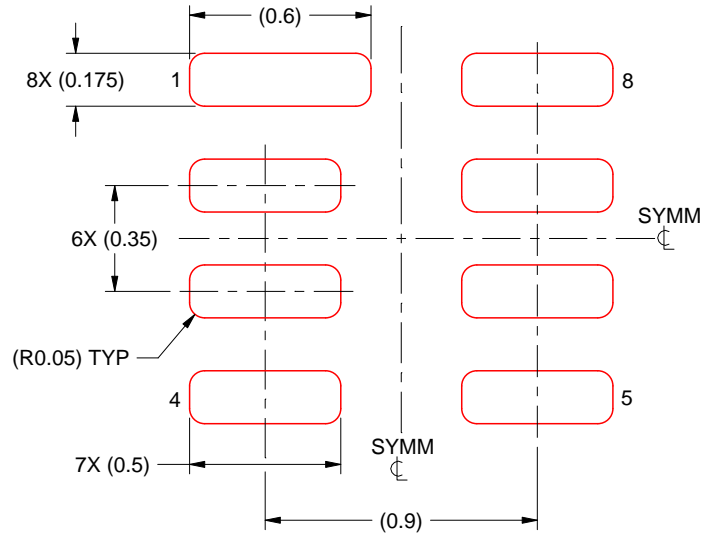
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).

# EXAMPLE STENCIL DESIGN

DQE0008A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.075 MM THICK STENCIL  
SCALE: 40X

4225204/A 08/2019

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

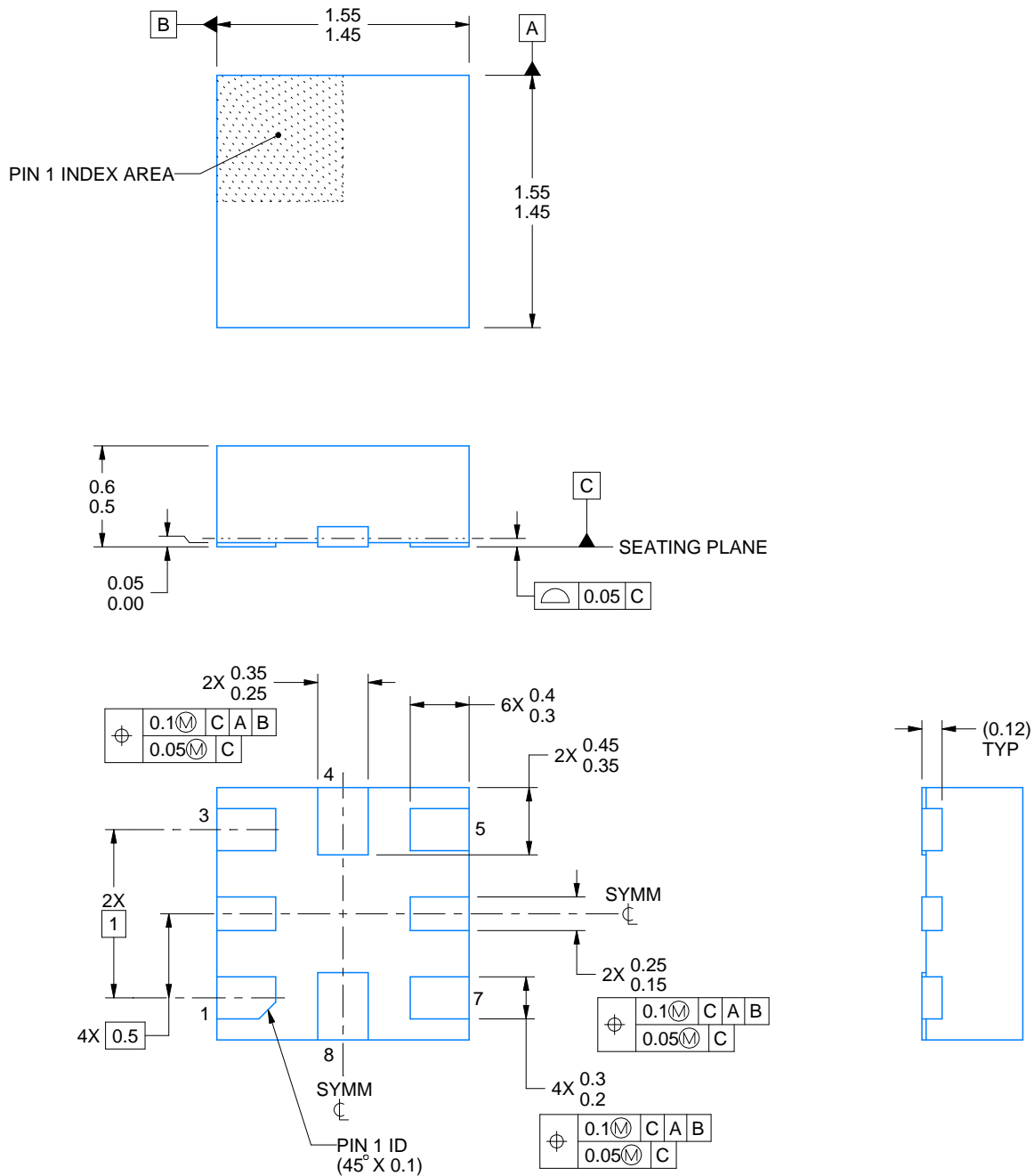
# RSE0008A



## PACKAGE OUTLINE

### UQFN - 0.6 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



4220323/B 03/2018

#### NOTES:

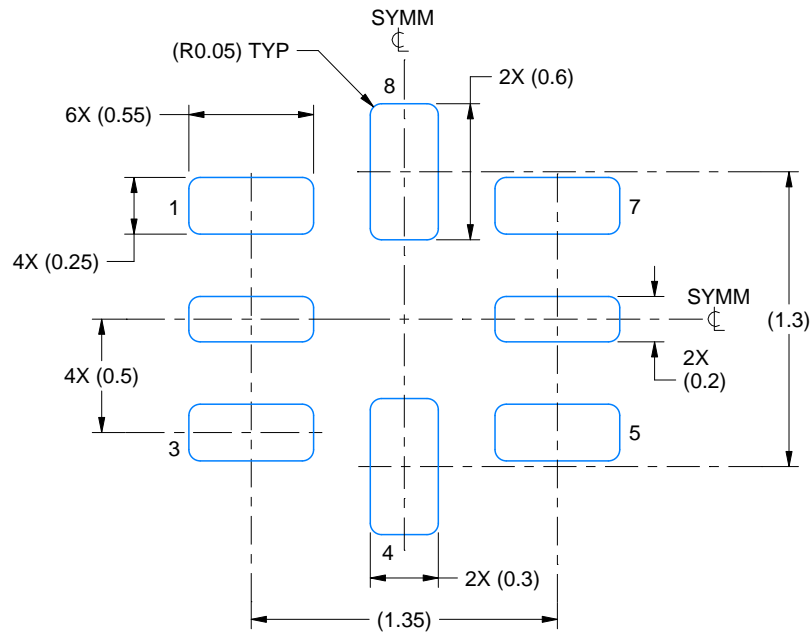
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

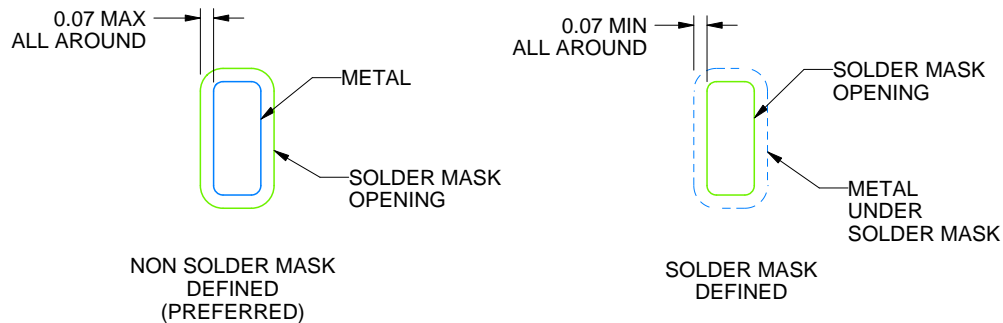
RSE0008A

UQFN - 0.6 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
SCALE:30X



SOLDER MASK DETAILS  
NOT TO SCALE

4220323/B 03/2018

NOTES: (continued)

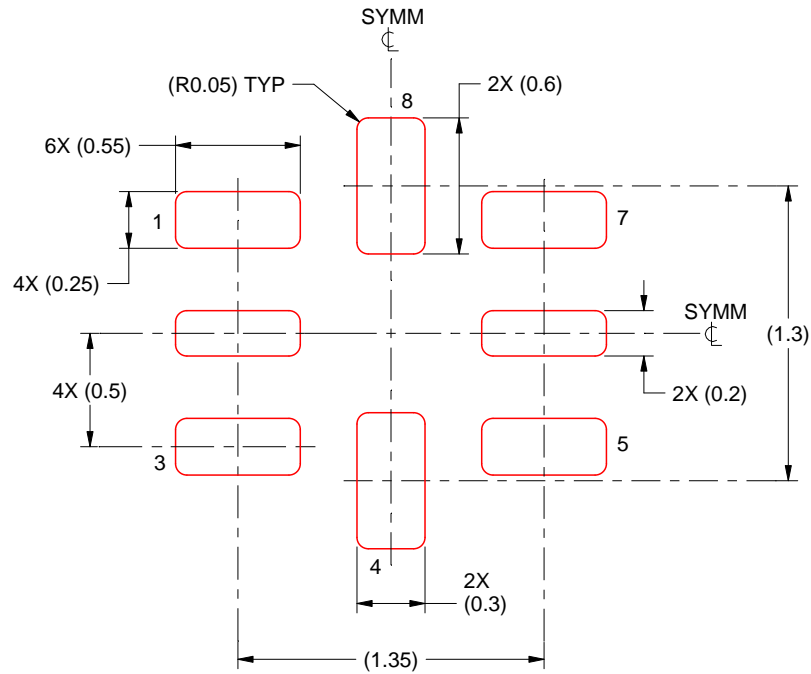
3. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slue271](http://www.ti.com/lit/slue271)).

# EXAMPLE STENCIL DESIGN

RSE0008A

UQFN - 0.6 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICKNESS  
SCALE: 30X

4220323/B 03/2018

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

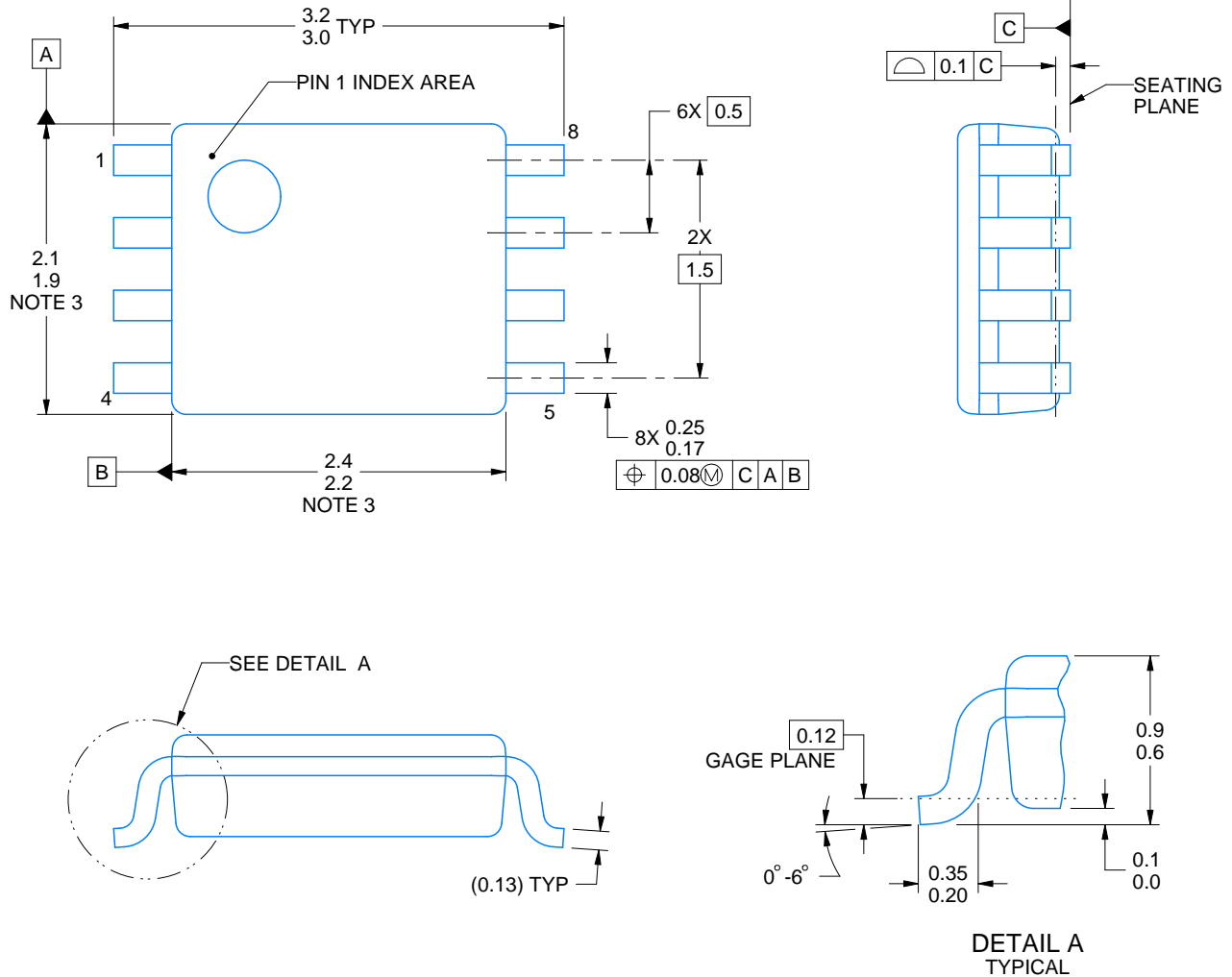
DCU0008A



## PACKAGE OUTLINE

VSSOP - 0.9 mm max height

SMALL OUTLINE PACKAGE



4225266/A 09/2014

### NOTES:

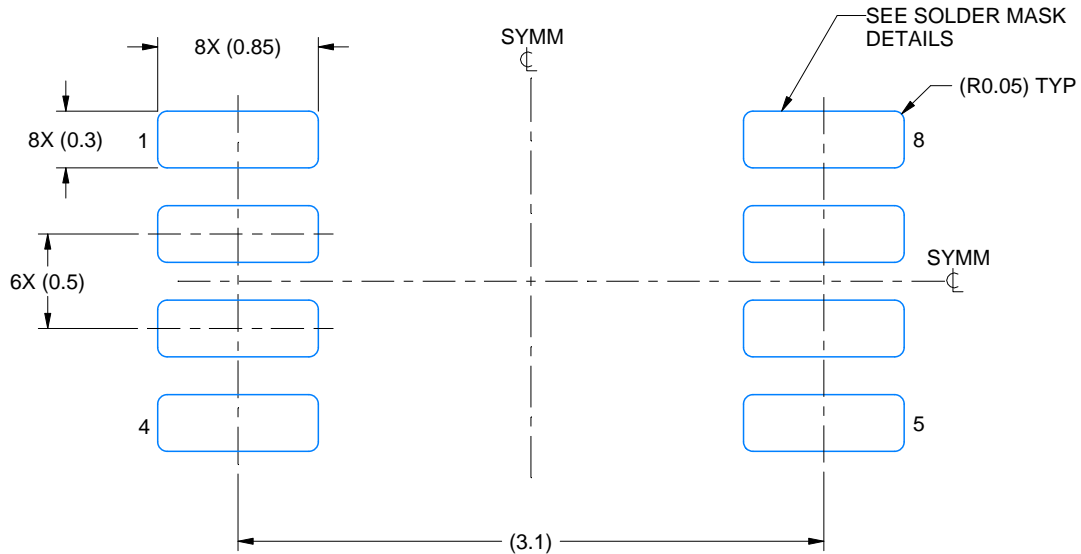
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-187 variation CA.

# EXAMPLE BOARD LAYOUT

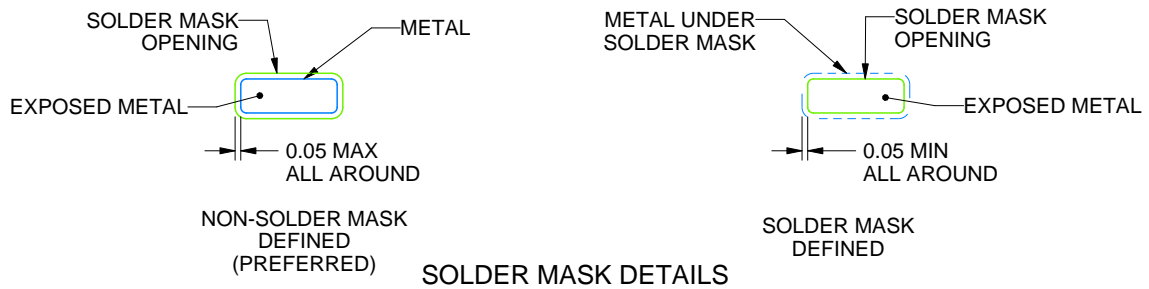
DCU0008A

VSSOP - 0.9 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 25X



4225266/A 09/2014

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

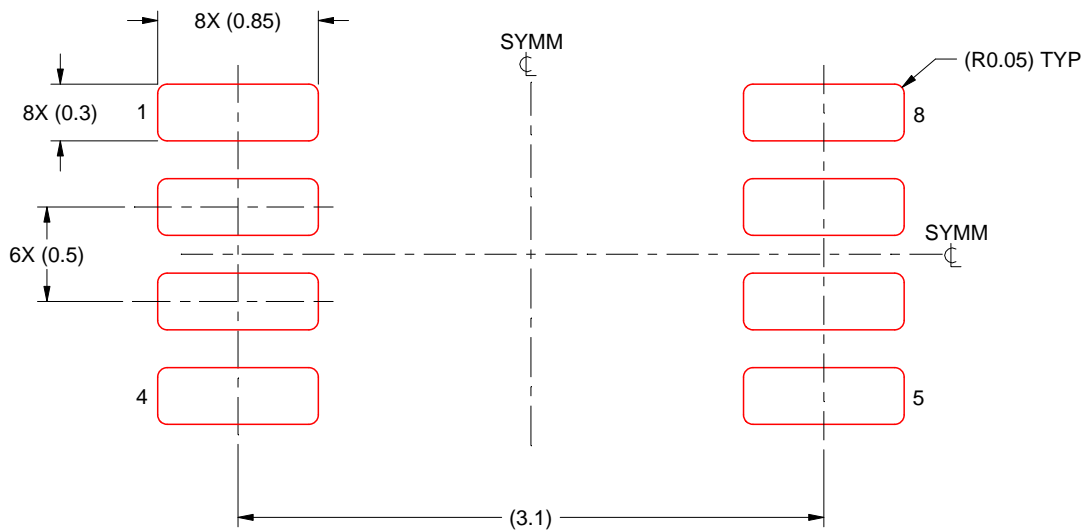
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DCU0008A

VSSOP - 0.9 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 25X

4225266/A 09/2014

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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